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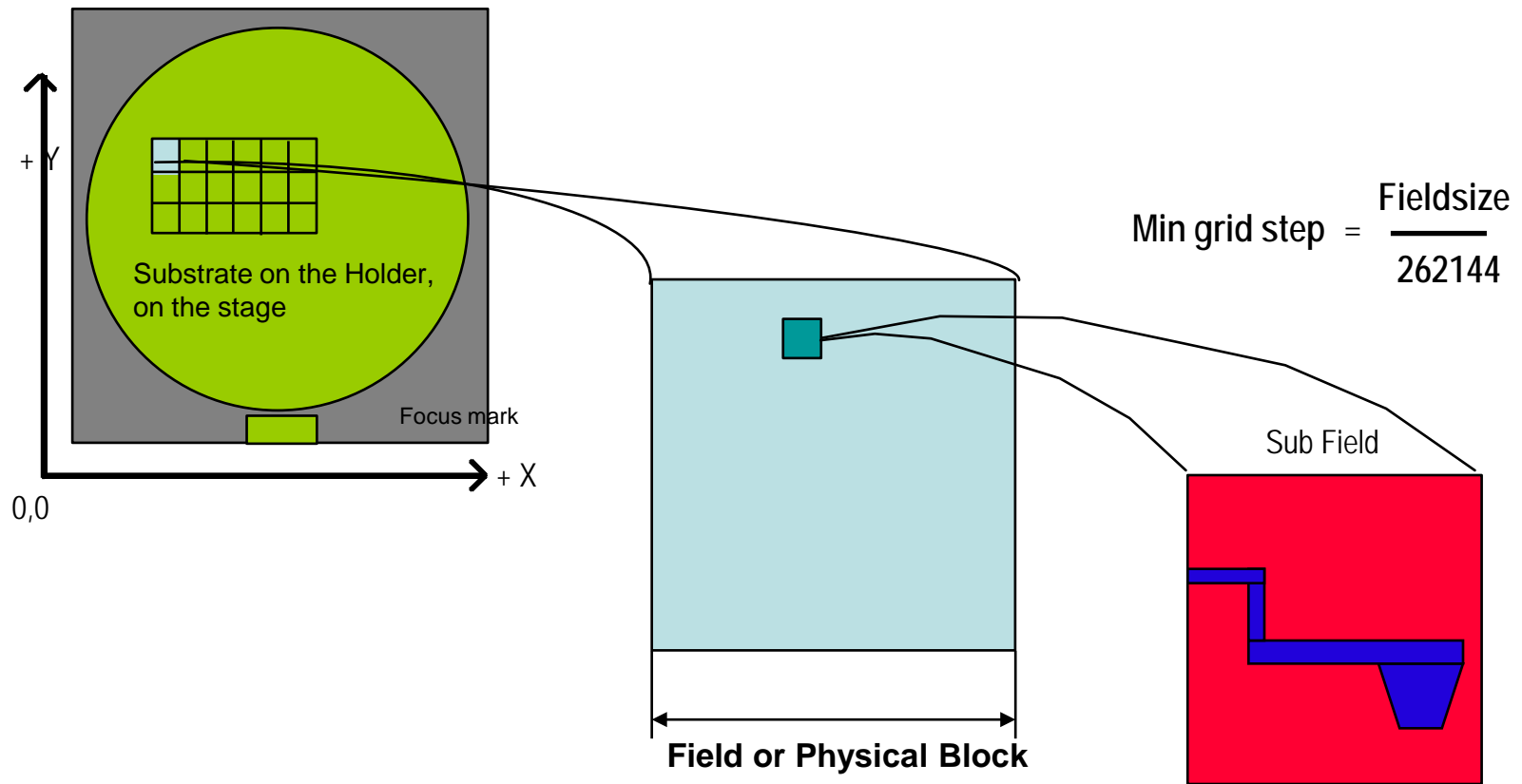
# Nanometer Scale Patterning and Processing

Spring 2016

## Lecture 20

### Vector Beam Performance and Operation (continued)

# Writing Strategy (Wide Field)



1. Stage moved to position of Field or Physical Block within pattern.

2. Sub-field positioned by Main deflection scan

3. Subfield area scanned by "Trapezium scan coils"

# Dose Control

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The correct dose is achieved by setting the time duration that the beam dwells at each exposure point within the pattern.

This time duration is determined by the frequency of the **DOSE CLOCK**.

A clock frequency of 1MHz sets the exposure time per pixel to 1 micro-second.

A pattern shape containing 10,000,000 exposure points will take 1 Second to expose with a clock set to 10MHz.

The maximum frequency possible is 25MHz

The Dose required for correct exposure depends on the

- Resist Sensitivity

- Field Size

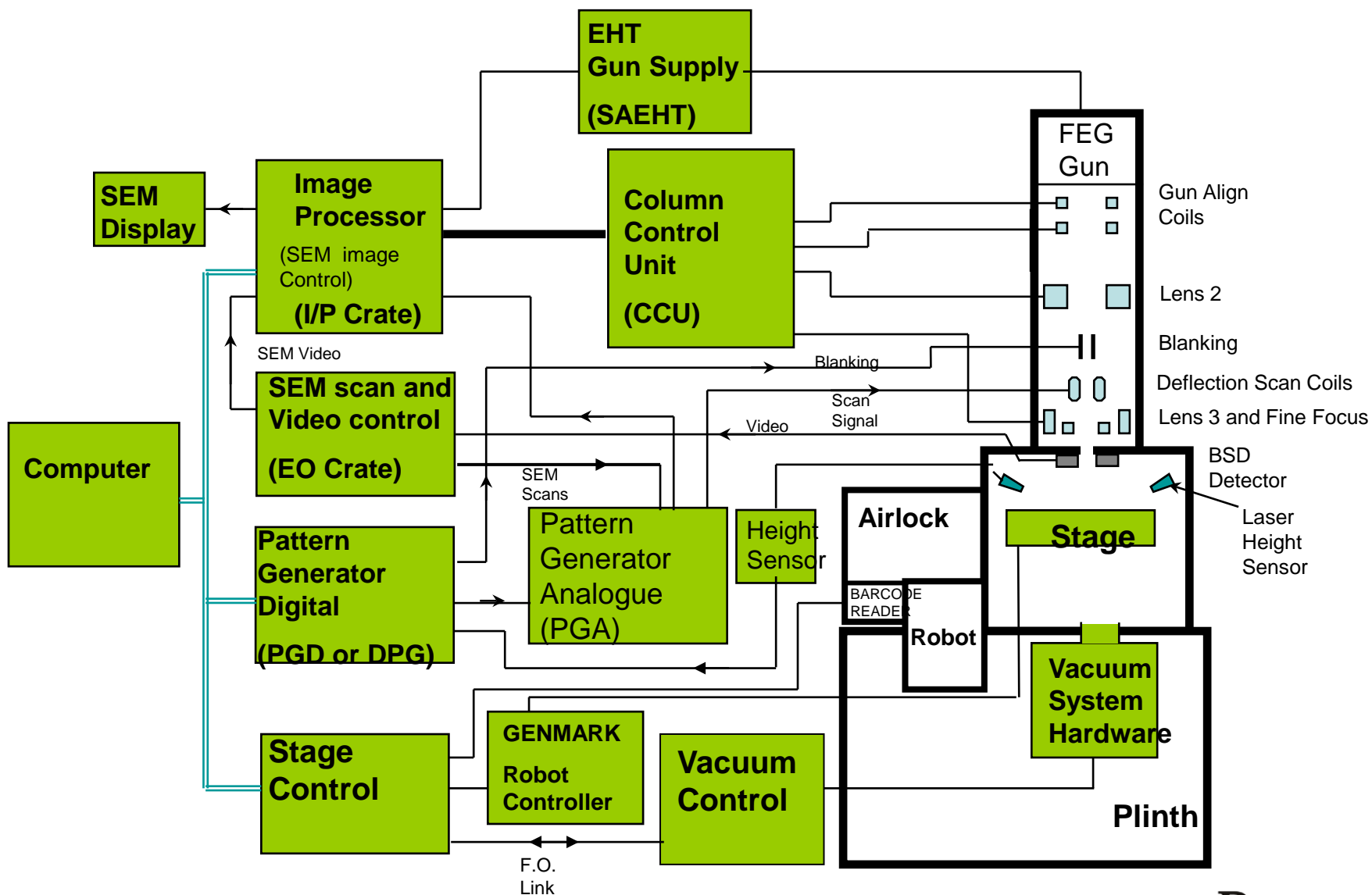
- Beam Current

- EHT

- Variable Resolution factor (VRU)

- Electron beam back-scatter

# Vectorbeam VB6 System Overview

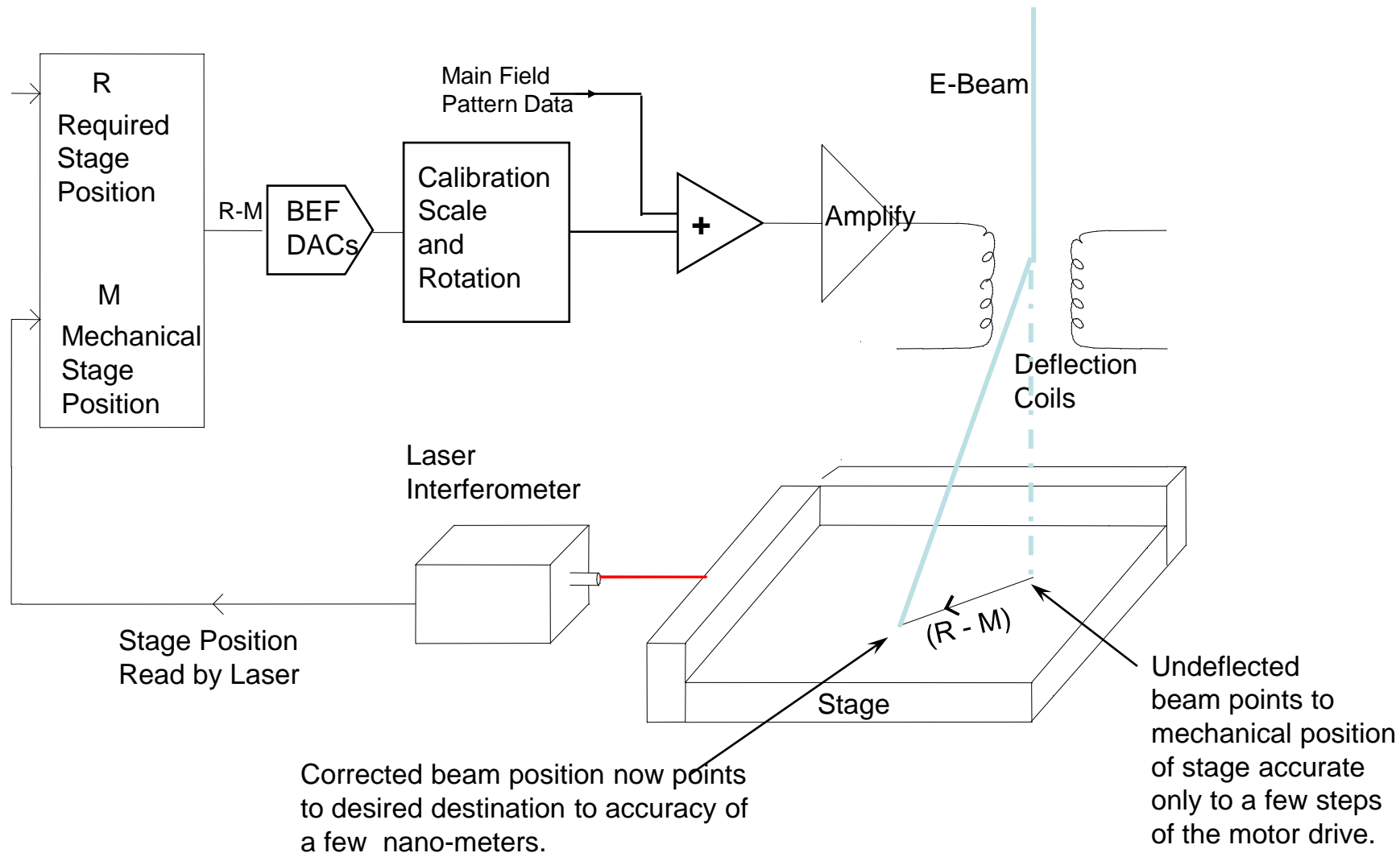


# Stage Position Error Correction

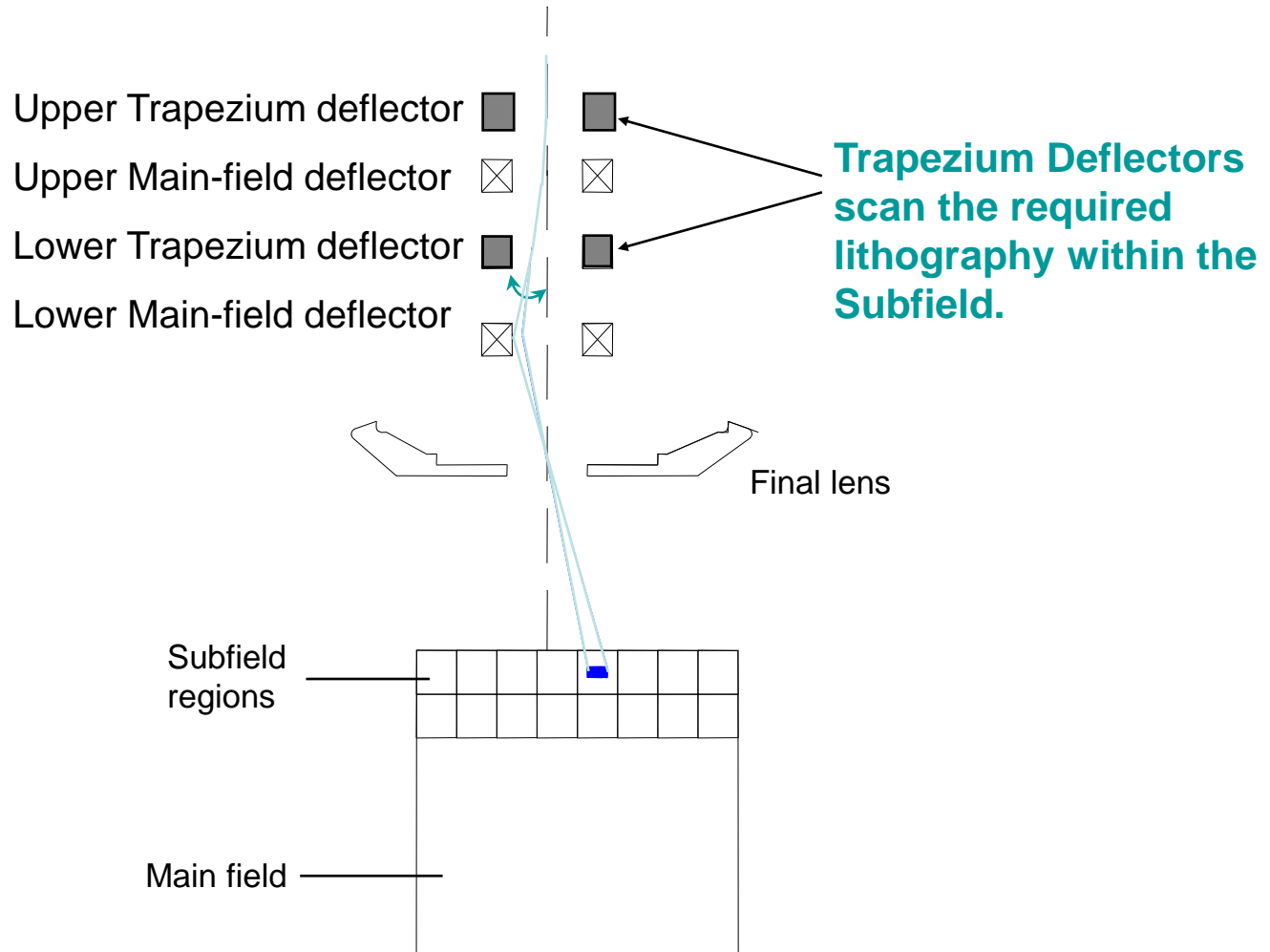
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- The Stage mechanical positional error is measured and then corrected for by deflecting the electron beam by a distance equal in magnitude and direction to this error. This results in it pointing to the exact coordinate position specified in the stage move.
- This is called “**Beam Error Feedback**” or “**BEF**”
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- Initial stage position error is measured and corrected by “Static” Beam Error Feedback.  
Range of Static BEF =  $\pm 20$  microns
- 
- Continuous monitoring of errors measures subsequent position errors.
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- Continuous correction of variable errors by “Dynamic” Beam Error Feedback
- Range of Dynamic BEF =  $\pm 5$  microns
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- Continuous monitoring of the stage position ensures continuous correction for any subsequent position errors - positional drift or small vibrations.

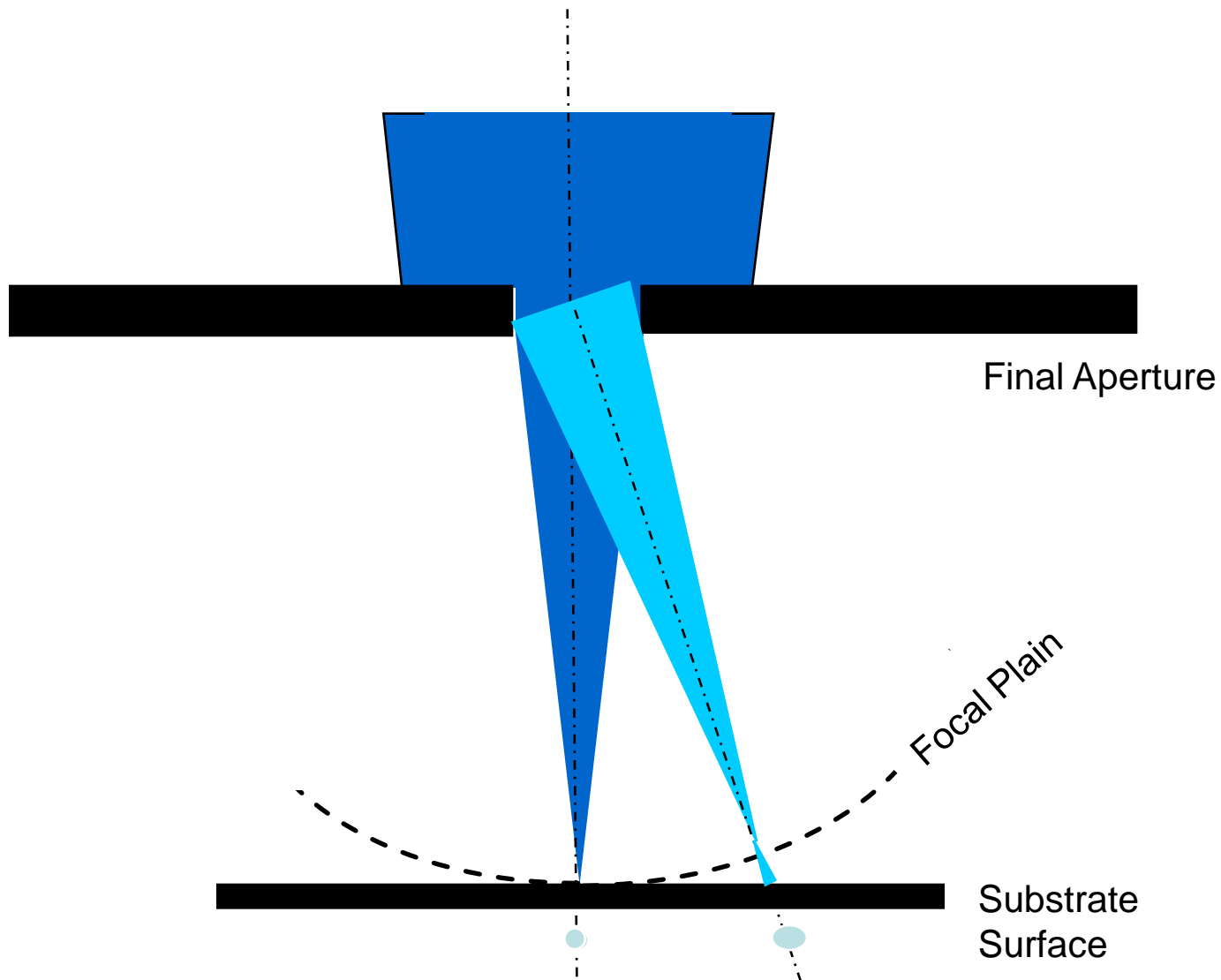
# Elements of Beam Error Feedback



# Exposure Scan Strategy (VB-UHR)

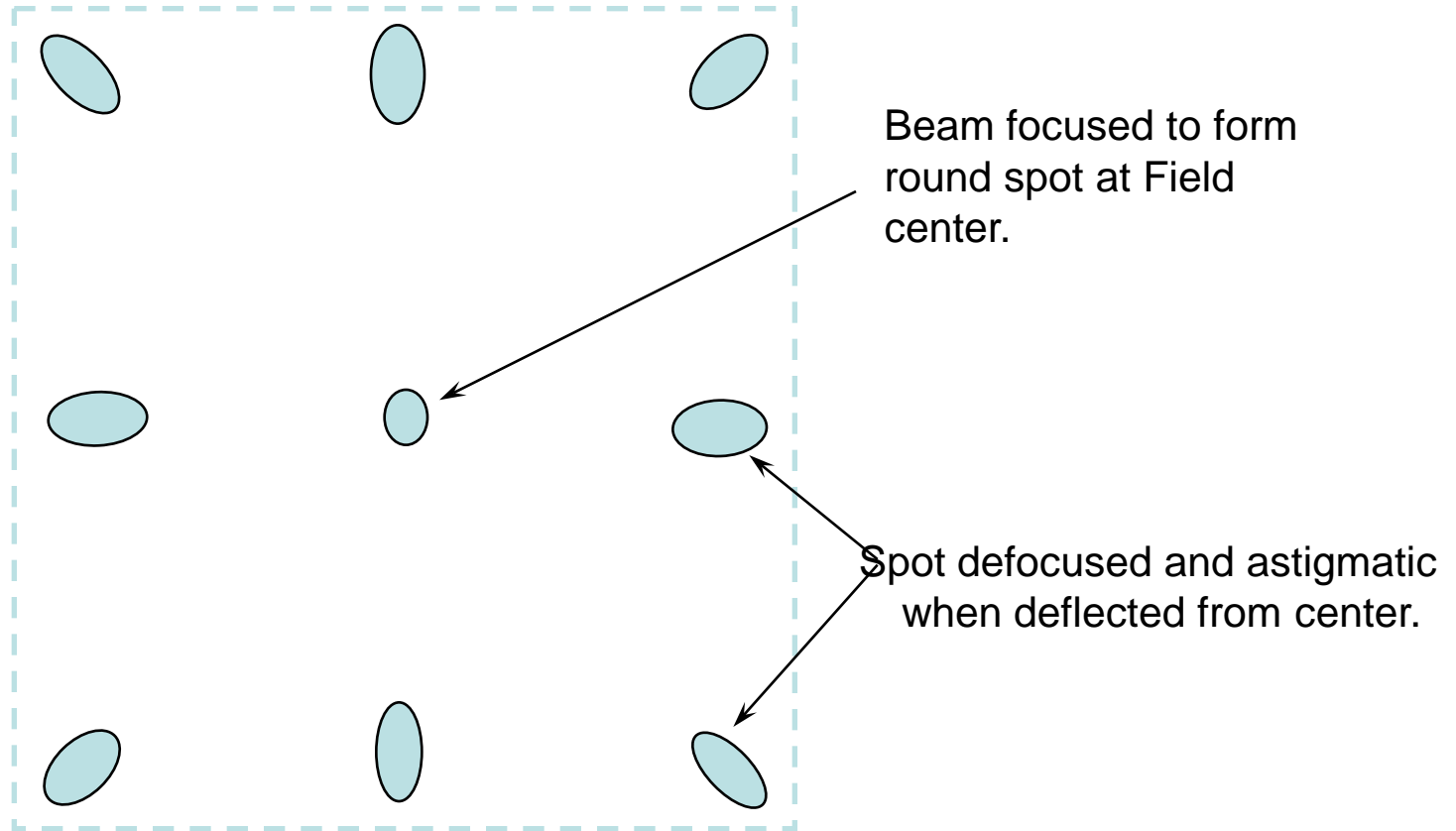


# Effect of Beam Deflection on the Beam





# Effect of Beam Deflection on the Focus

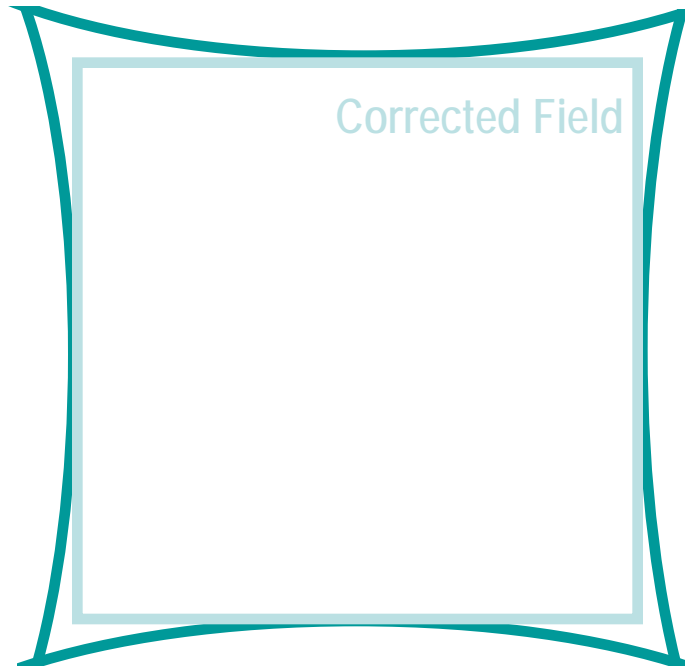


# Field Distortion caused by Beam Deflection

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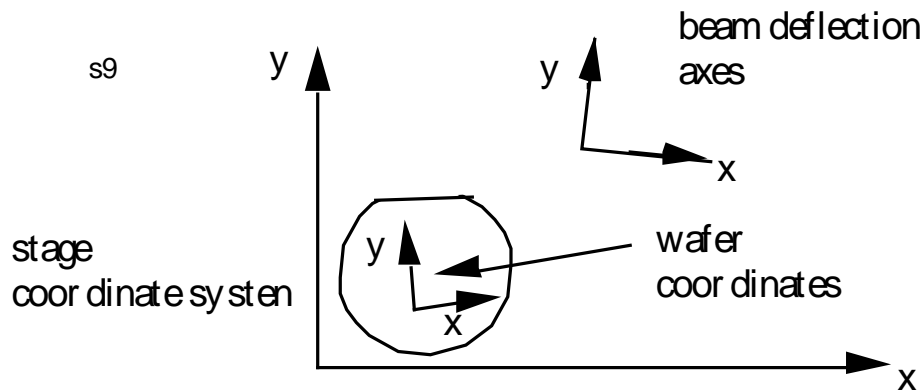
Distorted Field

Corrected Field

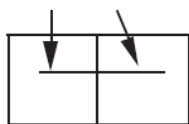


Field distortion is removed by applying corrections to the Main and Subfield scanning system

# Field Stitching and coordinate systems

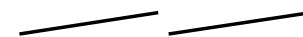
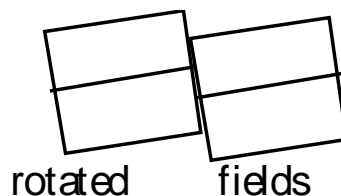


line spans two fields



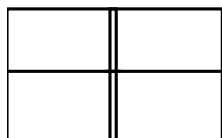
two fields

this results in a straight, continuous line if the scan and sample axes are aligned and magnification is correct



s11

Typically caused by focus change

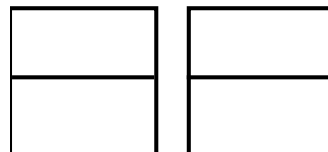


fields overlap

result



overexposure at overlap



s13

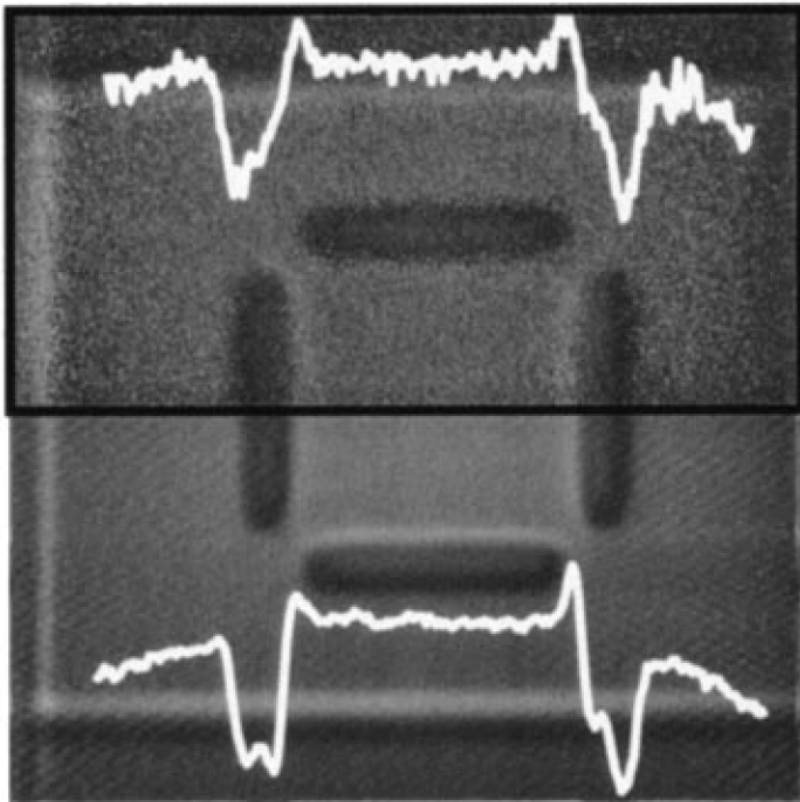


s12

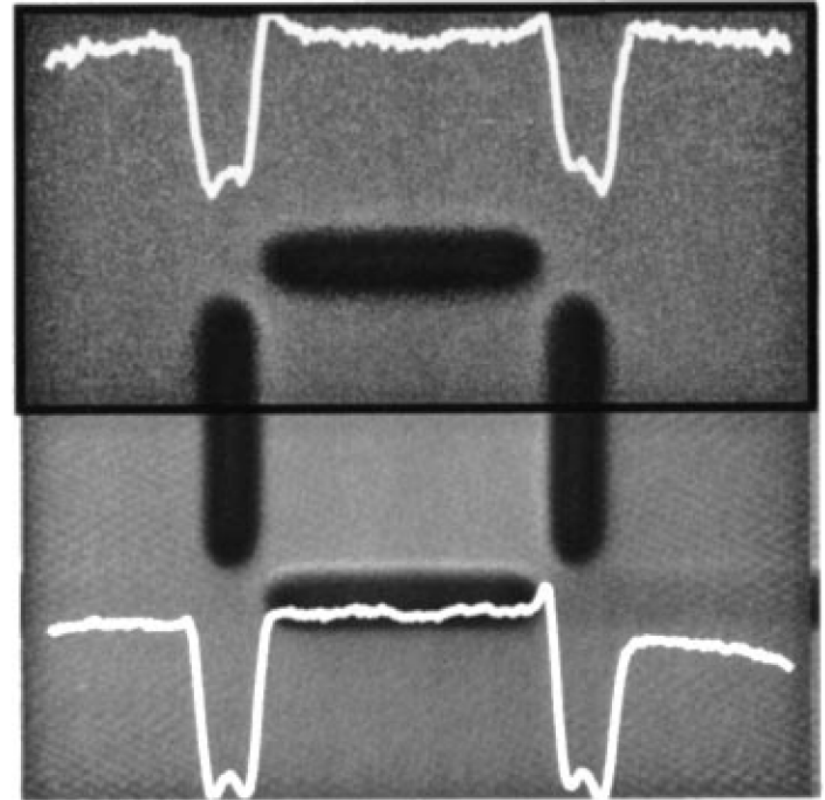
Field calibration is needed before exposure

# Detection of alignment marks

Low contrast

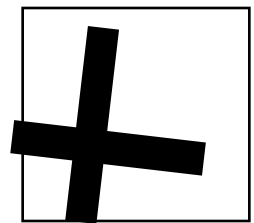
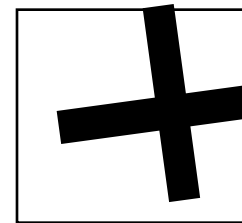
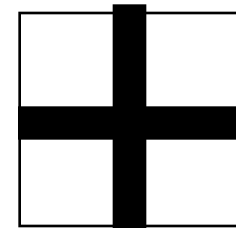
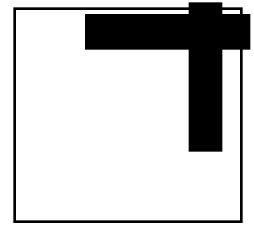
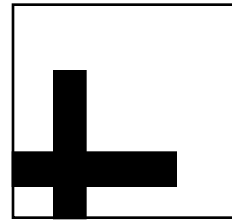
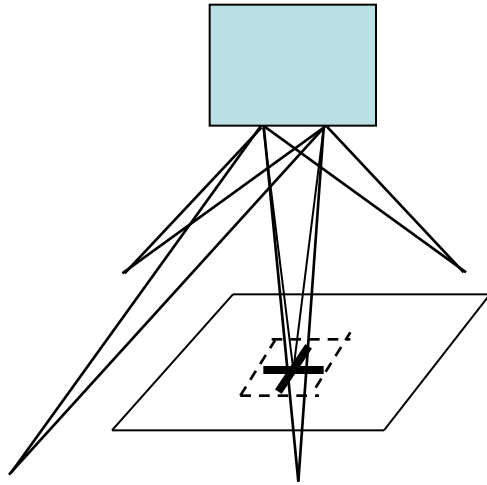


High contrast



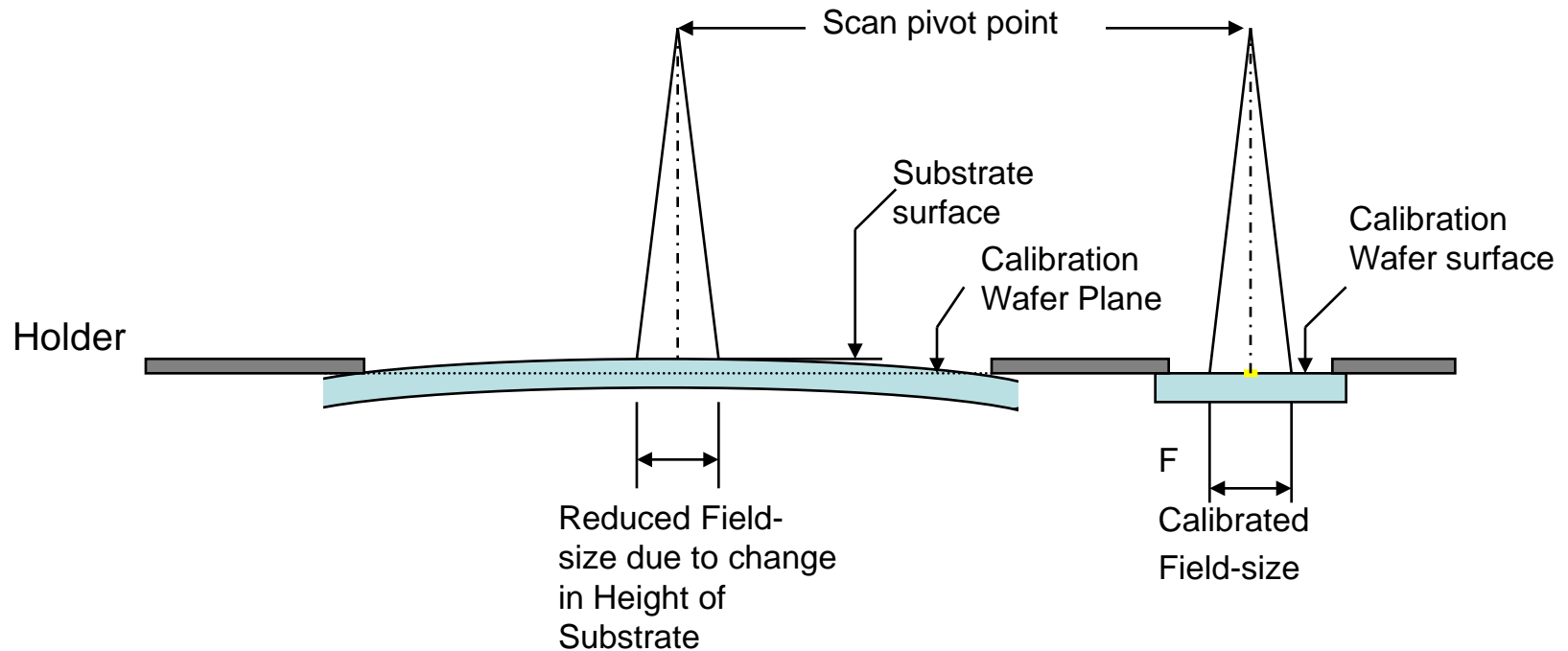
Algorithm looks for symmetry and calculates the center of the mark

# Field Calibration and Alignment



- Align the deflection directions along the stage coordinates
- Also can align to marks defined in previous layers

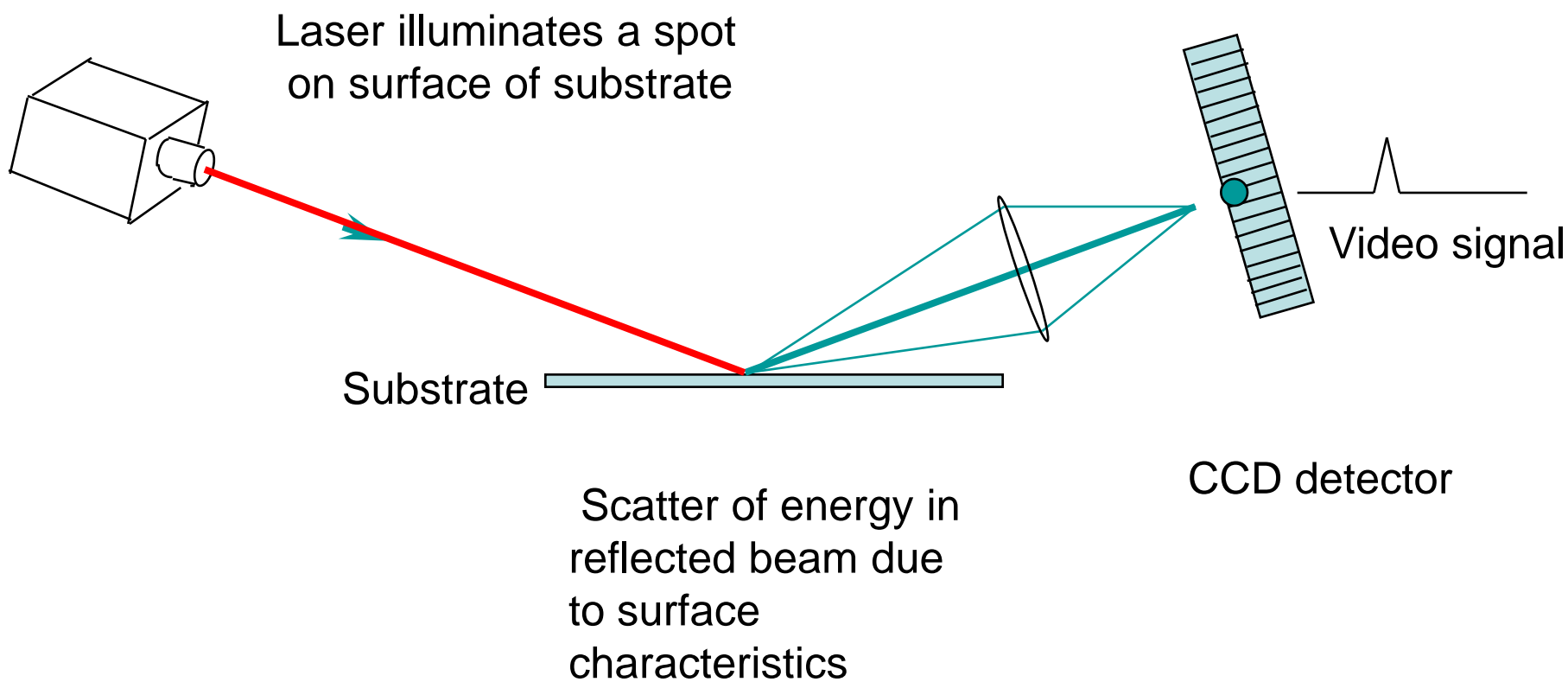
# Effects of Substrate Height Variation



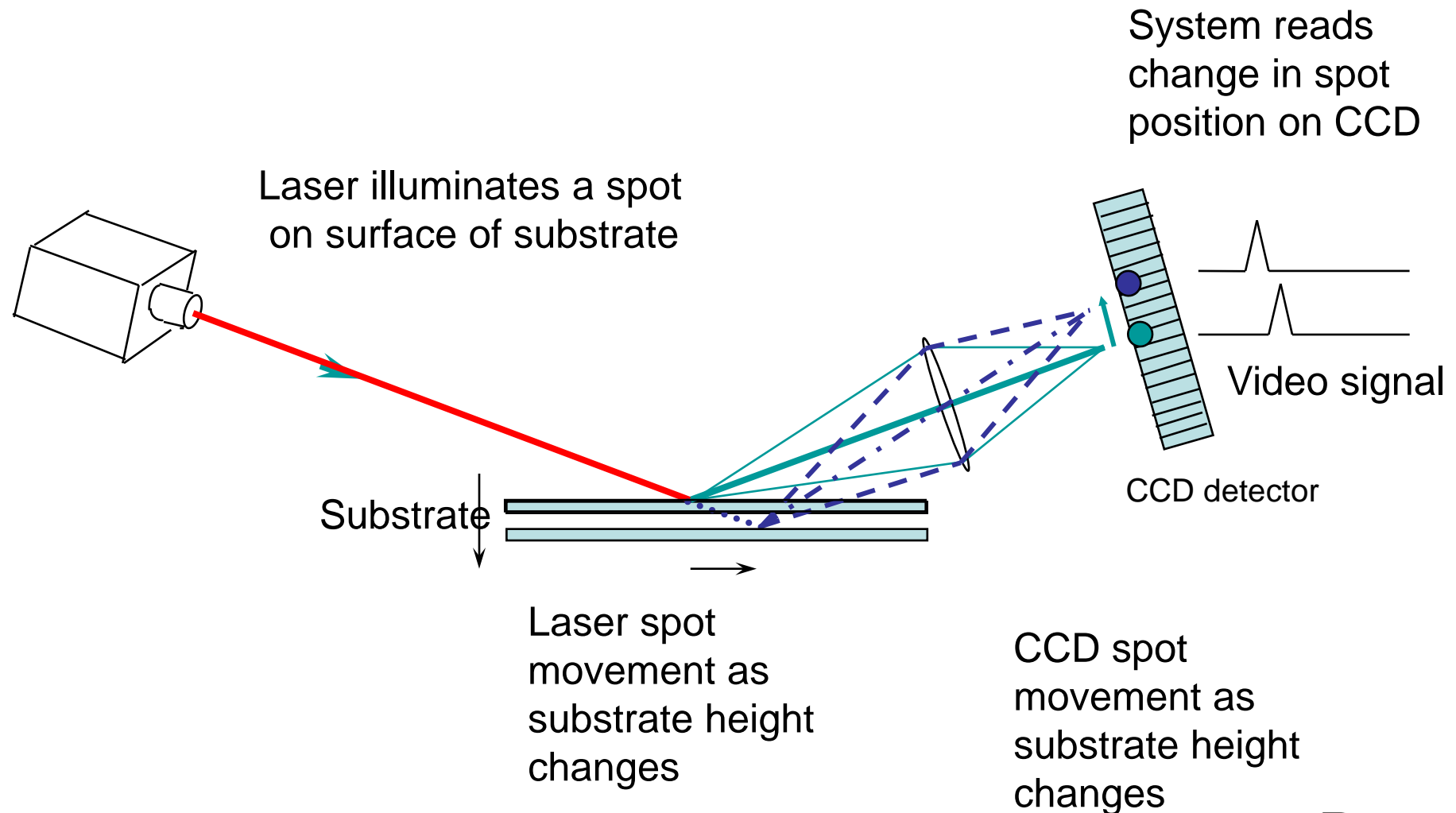
Changes in Substrate surface height relative to plane of the Calibration wafer result in

- a) Incorrect Field size
- b) Defocused beam

# Laser Height Sensor

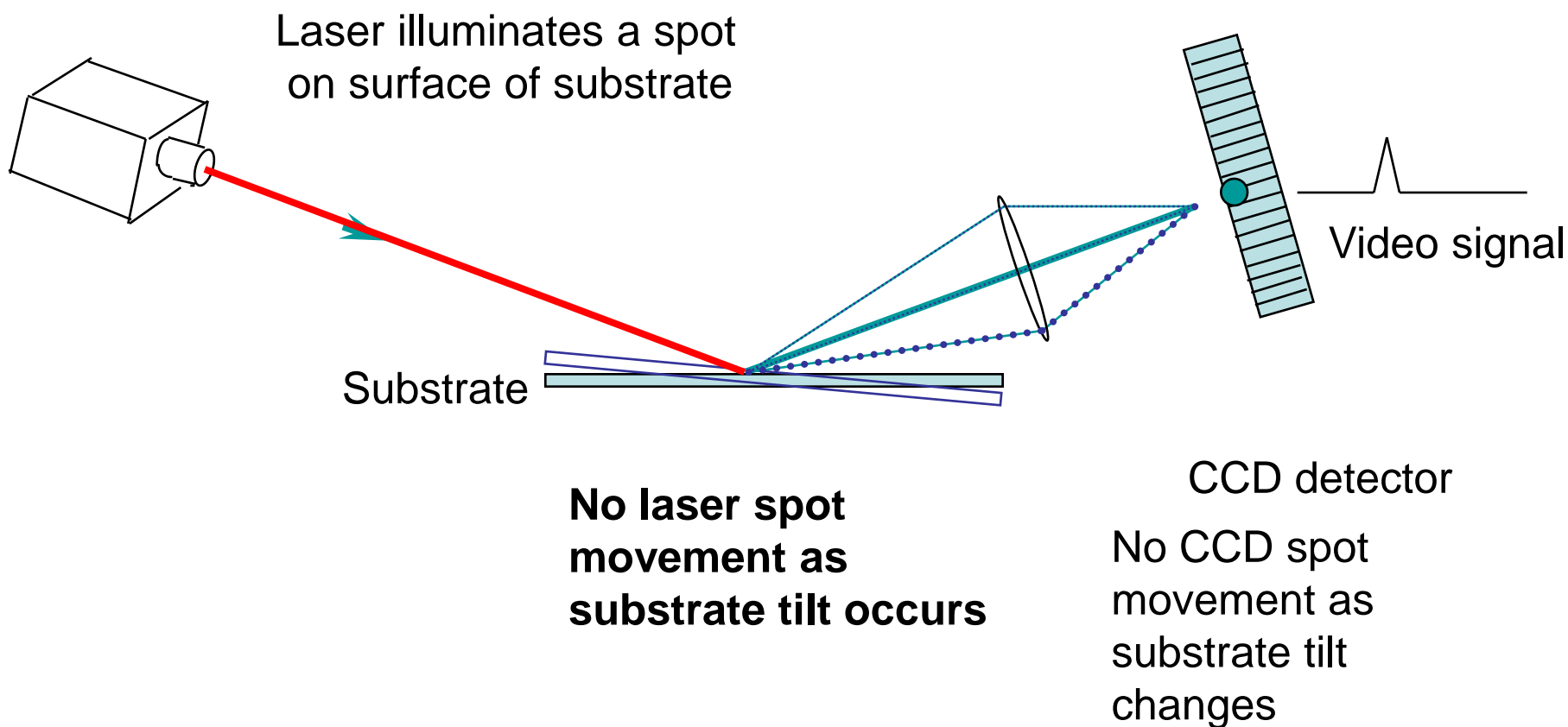


# Laser Height Sensor

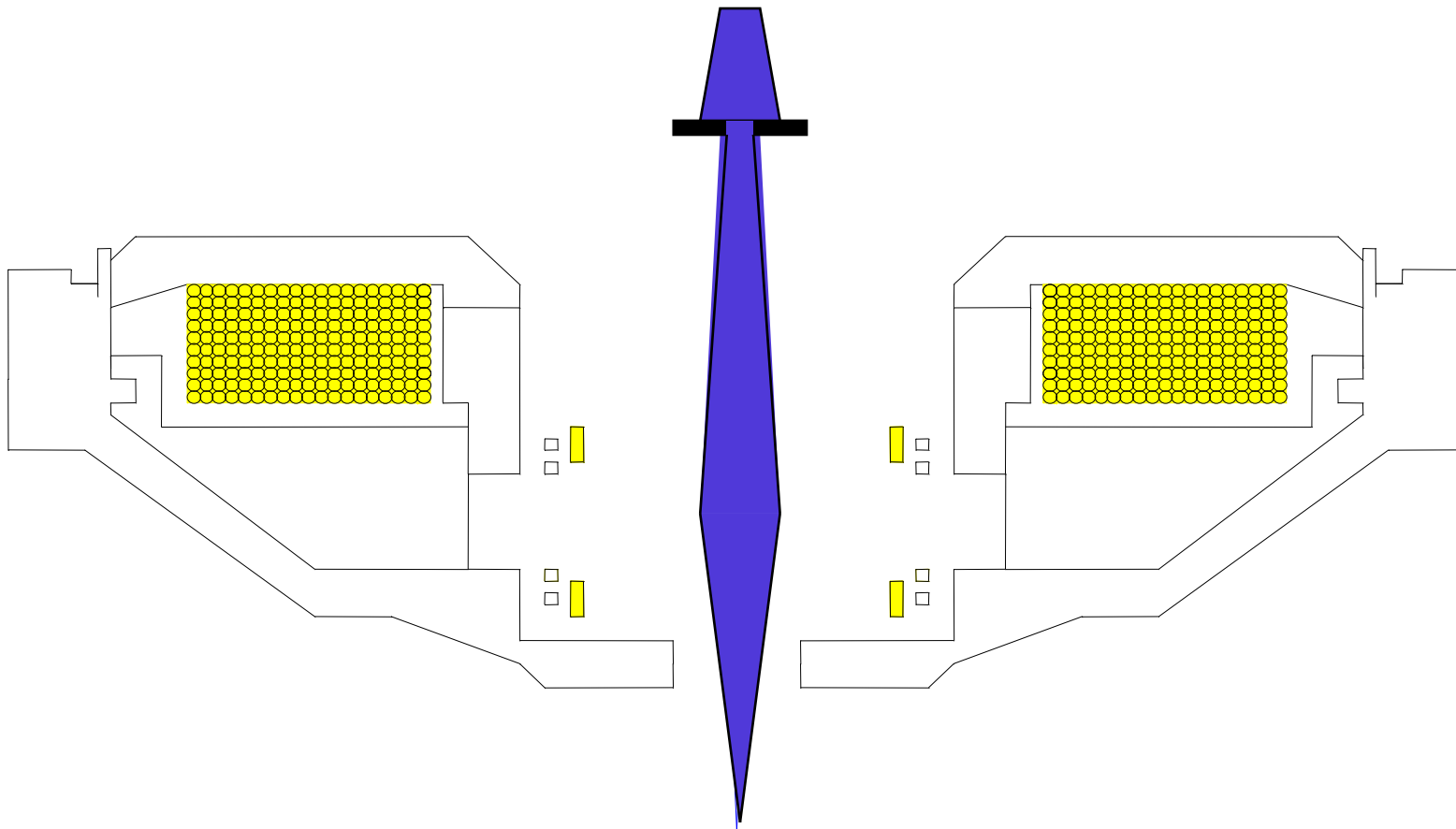




# Laser Height Sensor

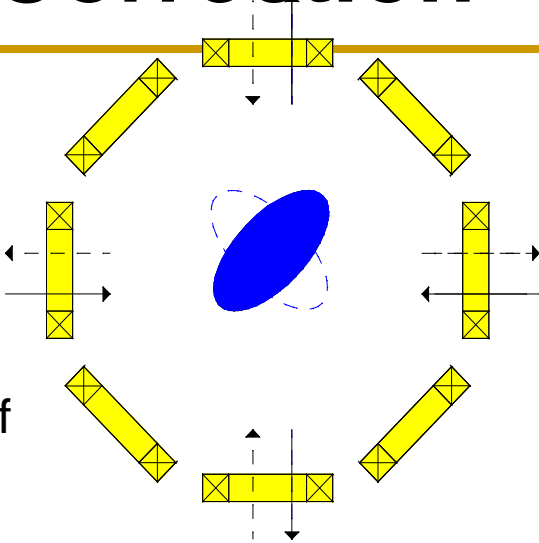


# Final (Focus) Lens 3



- The Final Lens focuses the electron beam onto the surface of the substrate. It consists of concentric lenses. The outer lens is the main one, for coarse focus; the inner lens is for automatic fine focus.
- A six ( "Final" ) aperture is located above the lens construction.
- The stigmation correction coils are also located here.

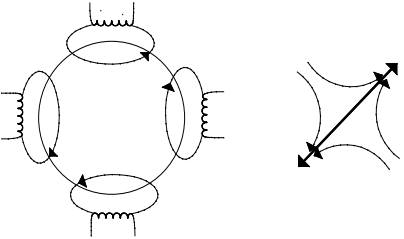
# Stigmatism Correction



2x4 STIGMATOR  
COILS IN FINAL  
LENS

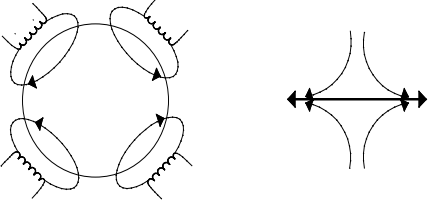
By adjusting the strength of the magnetic field in the 8 coils the beam can be “squeezed” in the direction required for correcting the astigmatic beam.

STIGMATOR COILS



Resultant  
field

Diagonal stigmator coils



Resultant  
field

Axis stigmator coils

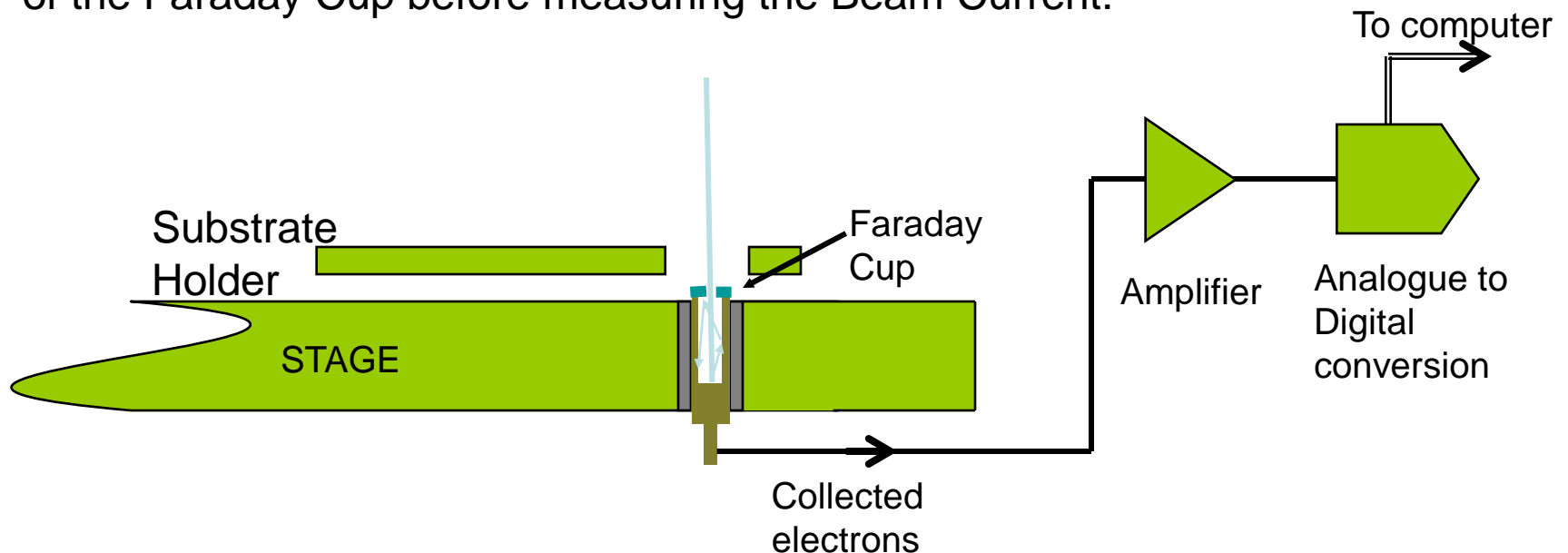
# Current Measurement

Beam current is measured by the “Faraday Cup” mounted in the Stage below the Substrate Holder.

The Faraday Cup is isolated from the Stage and designed to trap all electrons entering it.

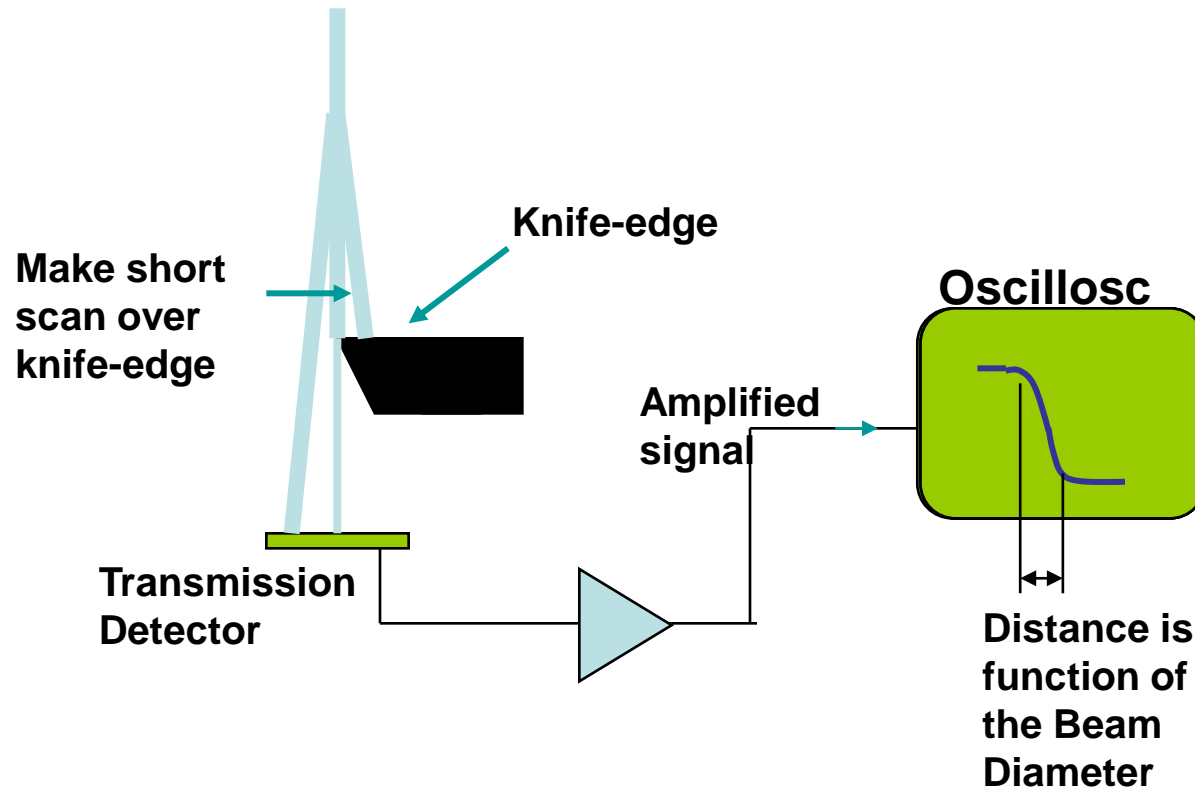
If the electron beam is not completely entering the Faraday Cup then a false measurement will result.

It is therefore essential that the stage is moved to the correct coordinate position of the Faraday Cup before measuring the Beam Current.



# Transmission Detector

- For facilitating the measurement of beam diameter a detector is mounted on the stage.
- When the beam is scanned across a knife-edge device on one of the substrate holders, the signal received from this detector changes between zero and maximum with a transient rate dependant on the beam diameter.



3~5 nm

# Corrections

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## Corrections are applied in real time for:

### Main field scan corrections

- Scale, rotation & keystone over the main field

### Trapezium field scan corrections

- Scale, rotation & keystone over the main field

### Focus and Astigmatism

- Focus and Stigmatism correction over main field
- Focus correction for each stage position dependant on substrate height

### Beam Error Feedback

- Scale and Rotation corrections dependant on mainfield deflection.

### Height

- Real time or Pre-map corrections of focus and deflection scan rotation

### Stage Position

- Beam Error Feedback
- Magnetic effect
- Orthogonality
- Machine mapping

# VB6 Pattern Manipulation System

